

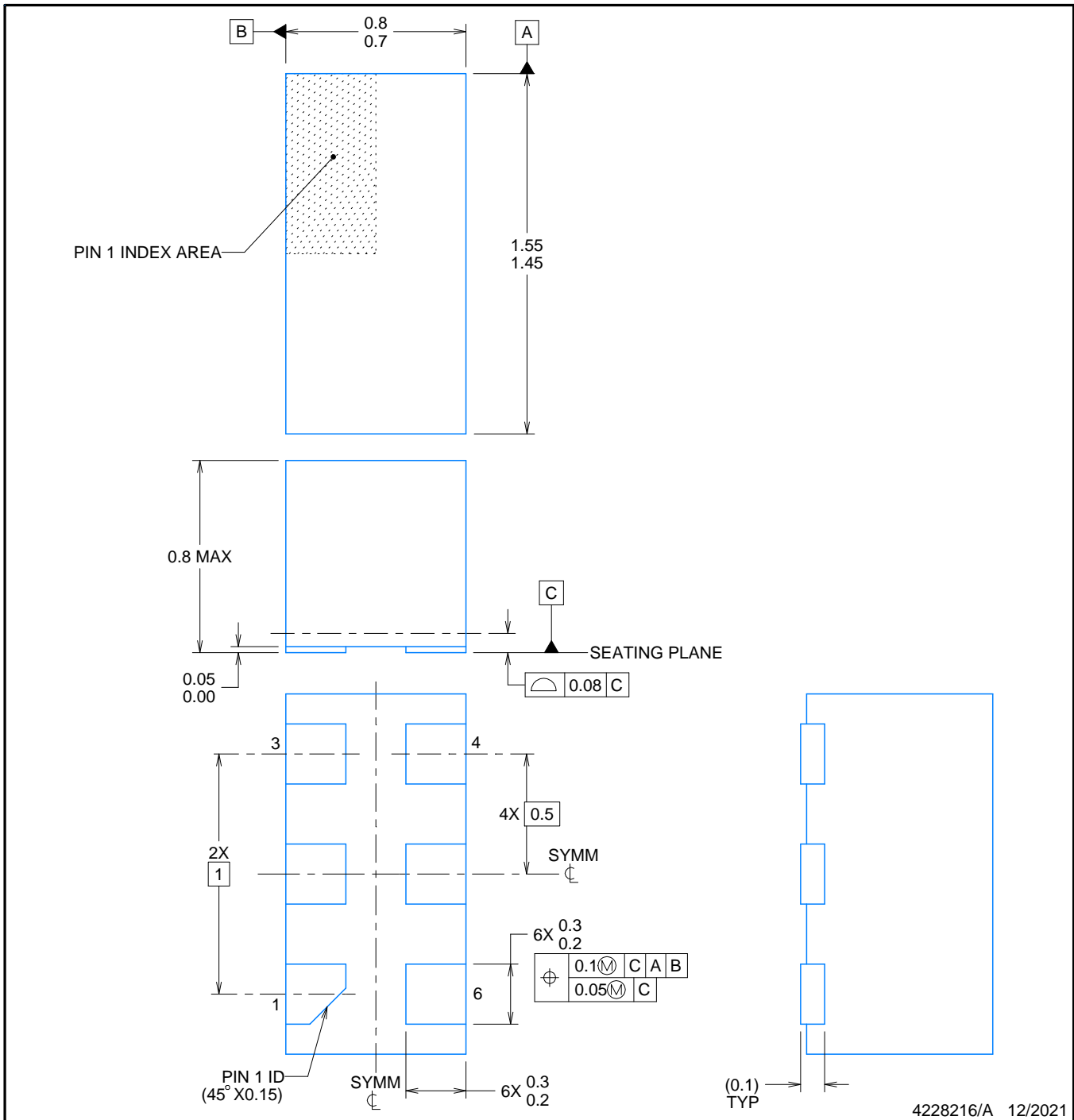
RZG0006A



PACKAGE OUTLINE

WQFN-HR - 0.8mm max height

QFN (PLASTIC QUAD FLATPACK - NO LEAD)



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NOTES:

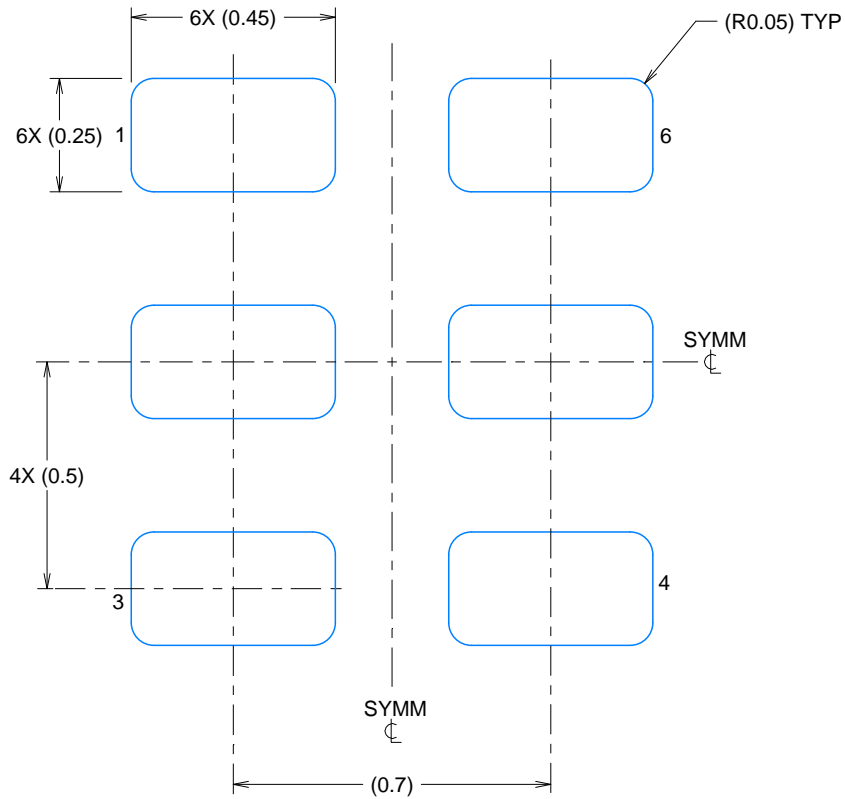
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

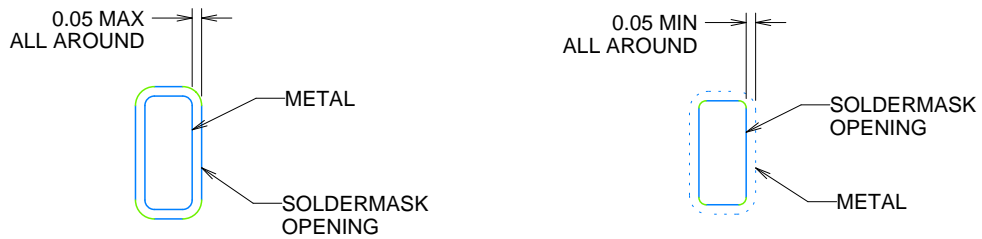
RZG0006A

WQFN-HR - 0.8mm max height

QFN (PLASTIC QUAD FLATPACK - NO LEAD)



LAND PATTERN EXAMPLE
SCALE:60X



NON SOLDERMASK
DEFINED
(PREFERRED)

SOLDERMASK
DEFINED

SOLDERMASK DETAILS

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NOTES: (continued)

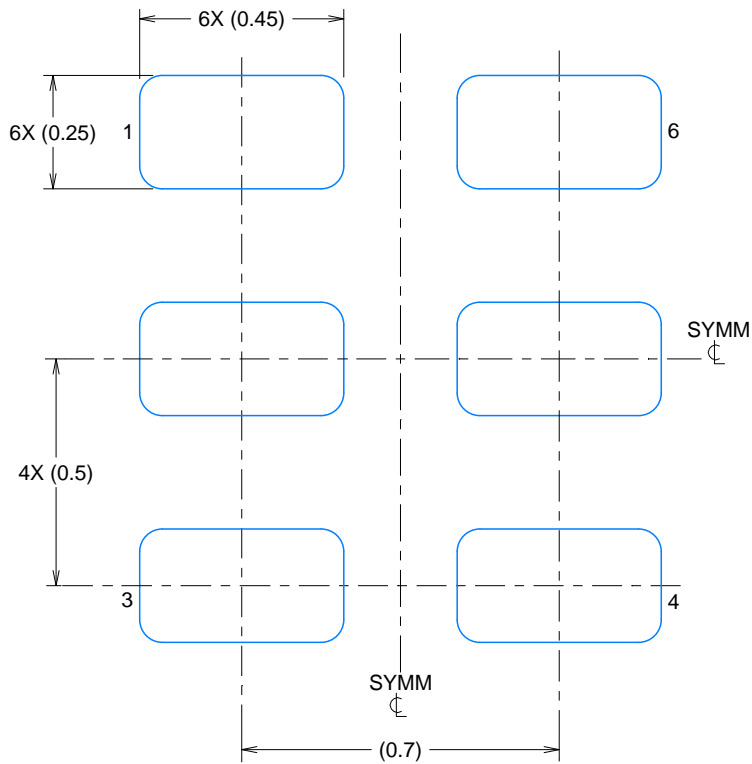
3. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

RZG0006A

WQFN-HR - 0.8mm max height

QFN (PLASTIC QUAD FLATPACK - NO LEAD)



SOLDERPASTE EXAMPLE
BASED ON 0.1mm THICK STENCIL

EXPOSED PAD
100% SOLDER COVERAGE BY AREA
SCALE:60X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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